

CLEANING SEMICONDUCTOR WAFERS

Abstract of the Disclosure

A wafer that has been subjected to chemical mechanical polishing may be cleaned by positioning it between a pair of counter-rotating brushes. A cleaning solution is
5 applied through the center of the brushes as the brushes rotate. As a result, in some embodiments, wafer defect density may be reduced, cleaning chemical residue buildup can be reduced, brush lifetime may be increased, and cleaning effectiveness may be improved.